

## 求人情報

スタッフレベル

ポジション名	Product Marketing Manager - Global Semiconductor - Up to 15M
この求人情報の取扱い会社	マイケル・ページ・インターナショナル・ジャパン株式会社/Michael Page International Japan K.K.
企業名	会社名非公開
掲載開始・更新	2024-05-13 / 2024-05-13
職種	IT関連（組込み/制御系） - プロジェクトマネージャー
業種	半導体・電気・電子部品メーカー
勤務地	アジア 日本 東京都
仕事内容	<p>Lead product marketing efforts for advanced Digital Lithography Technology (DLT) tools, targeting back-end packaging processes for innovative copper clad laminate (CCL) circuit boards. Collaborate with global partners, including a leading technology provider, to drive market penetration and shape the future of semiconductor packaging.</p> <p>Description</p> <ul style="list-style-type: none"><li>* Develop comprehensive business and marketing plans to drive competitive advantage and market share.</li><li>* Conduct detailed competitive analysis for specific product lines in Advanced Packaging.</li><li>* Establish pricing strategies and develop marketing tools for successful product introductions.</li><li>* Collaborate with cross-functional teams to develop and enhance products, and communicate critical market needs.</li><li>* Manage field support to optimize account partnerships and penetration opportunities.</li></ul> <p>Profile</p> <ul style="list-style-type: none"><li>* Possesses 5+ years of hands-on experience in semiconductor tool engineering, preferably in back-end packaging or front-end fab processes.</li><li>* Demonstrates strong technical knowledge and problem-solving skills, with the ability to communicate effectively with both internal and external stakeholders.</li><li>* Fluent in English, with proficiency in Japanese considered a plus.</li></ul> <p>Job Offer</p> <ul style="list-style-type: none"><li>* Competitive salary ranging from 9 to 15 million (total).</li><li>* Opportunity for international travel (50% domestic), excluding Okinawa and Hokkaido.</li><li>* Reporting directly to a non-Japanese Managing Director based in the US.</li><li>* First position in Japan, offering autonomy and leadership in a standalone role.</li><li>* Chance to influence the direction of cutting-edge technologies and shape the future of semiconductor packaging.</li></ul> <p>To apply online please click the 'Apply' button below. For a confidential discussion about this role please contact Maika Someda on +81 3 6832 8682.</p>
企業について(社風など)	Our client is a renowned player in the semiconductor industry, driving innovation and pushing boundaries in advanced packaging technologies. With a global presence and a commitment to excellence, they offer a dynamic environment where talented professionals can thrive and make a significant impact.
勤務時間	詳しくはお問い合わせください
応募条件	Possesses 5+ years of hands-on experience in semiconductor tool engineering, preferably in back-end packaging or front-end fab processes. Demonstrates strong technical knowledge and problem-solving skills, with the ability to communicate effectively with both internal and external stakeholders. Fluent in English, with proficiency in Japanese considered a plus.
英語能力	流暢 (TOEIC 865点以上)
日本語能力	ネイティブレベル
年収	日本・円 900万円 ~ 1500万円

